TO.: KUKE NO.: M230510



# APPROVAL SHEET

# MULTILAYER CERAMIC CAPACITOR Commercial Grade (Thin Layer Large-Capacitance Type) (IEC-60384 Qualified)

Approved by customer : (signing or stamping here)

SAM\	SAMWHA CAPACITOR CO., LTD.							
Writtern by	Writtern by Checked by Approved by							
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2023. 05. 10.

# SAMWHA CAPACITOR CO., LTD.

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< SPEC SUMMARY >								
SAMWHA Part no.		CS20	012X7R225K500NRE					
Type		Thin Lay	yer Large-Capacitance					
Item	Specification Unit Test methods and Conditions(Capacita							
Capacitance	2.2	μF						
Capacitance Tolerance	± 10	%	Testing Frequency: 1 ±0.1kHz Testing Voltage: 1 ±0.2Vrms					
Dissipation Factor	Max. 12.5	%						
Insulation Resistance	More than 22.7	MΩ	Applied the rated voltage for 2 minutes of charging.					
	2.00 ±0.20	L (mm)	, Consoitance Talarance Code					
Chip Size	1.25 ±0.15	W (mm)	*Capacitance Tolerance Code page 1/8  *Chip size page 2/8  *Characteristics 8 Test Method					
	1.25 ±0.15	T (mm)	*Characteristics & Test Method page 3/8~5/8					

Enactment :	STANDARD	NO	SW - M - 04B
March 27,1996	MULTILAYER CERAMIC CAPACITOR	Paga	1 / 0
,	Commercial Grade	Page	1 / 0

# 1. General Article

Application Range

These specifications refer to the "Multilayer Ceramic Capacitors "mainly used to the computer equipment, communication equipment.

\*Caution: Industrial equipment / For the high reliability equipment / LED equipment / Etc. Please contact sales representatives or product engineers before using the products. (For details, please refer Page 8)

# 2. General Code

(1) Type Designation

<u>CS</u>	<u>2012</u>	<u>X7R</u>	<u>225</u>	<u>K</u>	<u>500</u>	<u>N</u>	<u>R</u>	<u>E</u>
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)

- 1) Multilayer Ceramic Capacitor (Commercial Grade)
- 2) Size Code:

This is expressed in tens of a millimeter.

The first two digits are the length, The last two digits are width.

# 3) Temperature Coefficient Code

Classification	Code	Temperature Range	Capacitance Tolerance
Class I	COG	-55 to +125℃	±30 ppm/℃
	X5R	-55 to +85℃	±15%
	X7R	-55 to +125℃	±15%
Class II	X7S	-55 to +125℃	±22%
	X7T	-55 to +125℃	+22% ~ -33%
	Y5V	-30 to +85℃	+22% ~ -82%

## 4) Capacitance Code(Pico farads):

The nominal Capacitance Value in pF is expressed by three digit numbers.

The first two digits represents significant figures and the last digit denotes the number of zero ex) 104 = 100000 pF

R denotes decimal

8R2 = 8.2 pF

# 5) Capacitance Tolerance Code

Code	Tolerance
В	± 0.1 pF
С	± 0.25 pF
D	± 0.5 pF
F	± 1.0 %
G	± 2.0 %
J	± 5 %
K	± 10 %

Code	Tolerance
М	± 20 %
Р	+ 100, -0%
Z	+ 80, -20%
Н	+ 0.25/-0 pF
I	+ 0/-0.25 pF
U	+ 5/-0 %
V	+ 0/-5 %

6) Voltage Code

_														
code	6R3	100	160	250	350	500	101	201	251	501	631	102	202	302
Val	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC
Vol.	6.3V	10V	16V	25V	35V	50V	100V	200V	250V	500V	630V	1KV	2KV	3KV

7) Termination Code

ex) N: Ni-Sn (Nickel-Tin Plate)

A: Ag/Ni-Sn (Ag Epoxy/Nickel-Tin Plate) -> Soft Termination Type

8) Packing Code

ex) R: 7" Reel Type L: 13" Reel Type B: Bulk Type

9) Thickness option

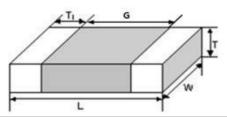
Thickne	Thickness(mm)		Thickne	Code	
t	Tol(±)	Code	t	Tol(±)	Ooge
0.30	0.03	Blank	1.30	0.20	Е
0.50	0.05	Blank	1.35	0.20	Н
0.60	0.10	А	1.60	0.20	I
0.80	0.10	В	1.80	0.20	J
0.85	0.15	В	2.00	0.25	K
1.00	0.15	Е	2.50	0.25	L
1.10	0.15	Е	2.80	0.30	М
1.15	0.15	Е	3.20	0.30	N
1.25	0.15	Е	5.00	0.40	0

# 3. Temperature Characteristics

See Page 5/8 (No.13)

# 4. Constructions and Dimensions

(I) Dimensions

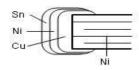


(Unit: mm)

	Dimension								
Code	Ler	ngth	Wi	dth	T1 (m; in)	O(min)			
	L	Tol(±)	$W$ $Tol(\pm)$ $T1(min$			G(min)			
0603	0.60	0.03	0.30	0.03	0.05	0.15			
1005	1.00	0.05	0.50	0.05	0.15	0.30			
1608	1.60	0.15	0.80	0.10	0.20	0.50			
2012	2.00	0.20	1.25	0.15	0.20	0.70			
3216	3.20	0.30	1.60	0.20	0.30	1.20			
3225	3.20	0.40	2.50	0.25	0.30	1.00			
4520	4.50	0.40	2.00	0.25	0.30	1.00			
4532	4.50	0.40	3.20	0.30	0.30	2.20			
5750	5.70	0.50	5.00	0.40	0.30	3.20			

\*2012 Size ≥10 $\mu$ F ⇒ W : 1.25±0.20, T : 0.85±0.15 \*3216 Size ≥47 $\mu$ F ⇒ W : 1.60±0.30, T : 1.60±0.30

# (2) Construction of Termination



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# Specifications and Test Methods (Thin Layer Large-Capacitance Type)

No.	Item		Specification	Test Methods and Conditions			
1	Operating Temperature Range		X7R, X7S, X7T : -55 to +125°C X5R : -55 to +85°C Y5V : -30 to +85°C				
2	Insulation Resistance		50Ω·F min	·Applied the rated voltage for 2 minutes of charging, The charge/discharge current is less than 50mA.			
3	Voltage proc	of	No defects or abnormalities	X7R, X7S, X7T, X5R, Y5V: The rated voltage × 250%  - Applied between the terminations for 1 to 5 seconds.  - The charge/discharge current is less than 50mA.			
4	Capacitance		within the specified tolerance	The capacitance/D.F. should be measured at 25°C at the			
5	Dissipation Factor		X7R, X7S, X7T, X5R : 12.5%max *3216 Size 100 <sub>≠</sub> F : 15%max Y5V : 20%max	frequency and voltage shown in the table.  Capacitance Frequency Voltage  C≤10  Frequency Voltage  C≤10  Frequency Voltage  C≤10  1 ± 0.1kHz 0.5~1.0Vrms  Frequency Voltage  0.5~1.0Vrms  Initial measurement  Perform the initial measurement  according to Note1 for Class II  Measurement after test  Take it out and set it for 24±2 hours (Class II)  then measure			
6	6 Solderability		95% of the terminations is to be soldered evenly and continuously.	*Pb-Free type Solder: 96.5Sn-3Ag-0.5Cu Solder temperature: 245±5°C Immersion time: 3±0.1sec *Pre-Heating: at 80~120°C for 10~30sec			
		Appearance Capacitance change	No defects which may affect performance  X7R, X7S, X7T, X5R: Within±7.5% Y5V: Within±20%	Preheat the capacitor at 120 to 150°C for 1 minute.  (Preheating for 3225,4520,4532  Step1:100°C to 120°C, 1min			
7	Resistance to Soldering Heat	Dissipation Factor	X7R, X7S, X7T, X5R : 12.5%max *3216 Size 100 <sub>\(\rho\)</sub> F : 15%max Y5V : 20%max	-260±5℃ for 10±0.5 seconds.  Initial measurement Perform the initial measurement according to Note1 for			
		I.R.	50Ω·F min	Class II  ·Measurement after test Let sit at room temperature for 24±2 hours,then measure.			
		Appearance	No defects which may affect performance	Perform the five cycles according to the four heat treatments listed in the following table.			
		Capacitance Change	X7R, X7S, X7T, X5R : Within ±7.5% Y5V : Within ±20%	Step 1 2 3 4  Min.  Temp operating Room operating Room			
8	Rapid Dissipatio Factor		X7R, X7S, X7T, X5R : 12.5%max *3216 Size 100 <sub>µ</sub> F : 15%max Y5V : 20%max	(°C)     temp.     Temp     temp.     Temp       +0/-3     +3/-0     +3/-0   Time (min) 30±3 2 to3 30±3 2 to3			
		I.R	50Ω·F min	Initial measurement Perform the initial measurement according to Note1 for Class II  Measurement after test Perform the final measurement according to Note2			

		Specification	Test Methods and Conditions				
Appearance		No defects which may affect performance					
	Capacitance Change	X7R, X7S, X7T, X5R : Within ±12.5% Y5V : Within ±30%	Apply 150% of the rated voltage for 1000+48/-0 hrs at the maximum operating temperature ±3°C. The charge/discharge current is less than 50mA.				
Endurance	Dissipation Factor	X7R, X7S, X7T, X5R : 20%max *3216 Size 100 ≠ : 30%max	-Initial measurement Perform the initial measurement according to Note1 for Class II				
	I.R	12.5Ω·F min	Measurement after test Perform the final measurement according to Note2				
Substrate bending test	Capacitance Change	Support  Solder Chip  Printed circuit board before testing  1.60 ± 0.20 m or 0.80 ± 0.10 m  R5  Printed circuit board under tost  No cracking or marking defects shall occur  X7R, X7S, X7T, X5R: Within ±10%  Y5V  Within ±30%  Within ±30%  Within ±30%  Within ±30%	·Substrate material : Glass EPOXY Board.  ·Thickness : 1.6mm     0.8mm(0603/1005size)  *. Test condition - Bending limit: 1mm - Pressurizing speed: 1mm/sec - Holding time: 5±1sec				
		No defects or abnormalities	After soldering and then let sit for 24±2hr at room temperature.				
	Сараспапсе	whili the specified tolerance	The capacitor should be subjected to a simple harmonic motion having a total amplitude of				
Vibration	Dissipation Factor	X7R, X7S, X7T, X5R : 12.5%max *3216 Size 100 <sub>\(\rho\)</sub> F : 15%max Y5V : 20%max	1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55Hz, shall be traversed(from 10Hz to 55Hz then 10Hz again) in approximately 1 minute. This motion shall be applied for a period of 2 hours in each 3mutually perpendicular directions(total is 6hours).				
	Appearance	No defects which may affect performance	Apply the rated voltage at 40±2°C and				
Accelerated	Capacitance Change	X7R, X7S, X7T, X5R: Within ±12.5% Y5V : Within ±30%	90 to 95%RH for 500+24/-0 hrs. The charge/discharge current is less than 50mA.				
damp heat, steady state	Dissipation Factor	X7R, X7S, X7T, X5R : 20%max *3216 Size 100μF : 30%max	Perform the initial measurement according to Note1 for Class II				
	I.R.	12.5Ω·F min	Measurement after test Perform the final measurement according to Note2				
	Substrate bending test  Vibration  Accelerated damp heat,	Endurance Change  Endurance Dissipation Factor  I.R  Substrate bending test  Capacitance Change  Appearance Capacitance Change  Appearance  Capacitance Change  Appearance Capacitance Change  Dissipation Factor  Appearance Change  Dissipation Factor	Endurance  Capacitance Change  X7R, X7S, X7T, X5R : Within ±12.5% Y5V : Within ±30%  X7R, X7S, X7T, X5R : 20%max +3216 Size 100 f : 30%max Y5V : 40%max  I.R  12.5Q:F min  Substrate bending test  No cracking or marking defects shall occur X7R, X7S, X7T, X5R: Within ±10% Y5V : Within ±30%  No cracking or marking defects shall occur X7R, X7S, X7T, X5R: Within ±10% Y5V : Within ±30% Within +30/-40% (cap≥10 f)  Appearance Capacitance Capacitance Whin the specified tolerance  Vibration  Dissipation Factor  X7R, X7S, X7T, X5R : 12.5%max +3216 Size 100 f : 15%max Y5V : 20%max  Accelerated damp heat, steady state  Dissipation Factor  X7R, X7S, X7T, X5R: Within ±12.5% Y5V : Within ±30% X7R, X7S, X7T, X5R: Within ±12.5% Y5V : Within ±30% X7R, X7S, X7T, X5R: Within ±12.5% Y5V : Within ±30% X7R, X7S, X7T, X5R: Within ±12.5% Y5V : Within ±30% X7R, X7S, X7T, X5R: 20%max +3216 Size 100 f : 30%max +3216 Si				

	No.	Item		Sp	ecification	Test Methods and Conditions			
			Char.	Temp. Range	Reference Temp.	Cap.	Change	The capacitance change should be measured after 5 min. at each specified temperature stage.	
	4.0	Temperature  characteristic  of capacitance	X5R	-55 to +85℃	25℃	Within	±15%	The ranges of capacitance change	
	13			X7R	-55 to +125℃	25℃	Within	±15%	compared with the 25°C value over the
			X7S	-55 to +125℃	25℃	Within	±22%	temperature ranges shown in the table	
			X7T	-55 to +125℃	25℃	Within	+22/-33%	should be within the specified ranges.	
			Y5V	-30 to +85℃	25℃	Within	+22/-82%	should be within the specifica ranges.	
ιl									

\*Note1. Initial Measurement for Class II

Perform a heat treatment at 150+0,-10°C for one hour and then let sit for 24±2 hours at room temperature, then measure

\*Note2. Measurement after test

Perform a heat treatment at 150+0,-10°C for one hour and then let sit for 24±2 hours at room temperature, then measure.

"Following the International standards, the title of each test item is subject to change."

# 5. Packing

- (1) Bulk packing
  - 1 1000 pcs per Polybag
  - 2 5 Polybags per Inner box
  - 3 10 Inner boxes per Out box
- (2) Reel Packing
  - ① 8~10 Reels per Inner box
  - 2 6 Inner boxes per Out box
- (3) Reel Dimensions



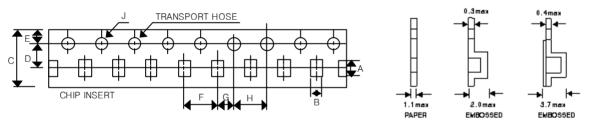


						(L	Jnit: mm)
MARK	SIZE	Α	В	С	D	Е	W
7 " RFFI	0603~3225	Φ178±2	Φ50Min	Ф13±0.5	Φ21±0.8	2±0.5	10±1.5
/ REEL	4520~4532	Ф180+0,-3	Ф60-0,+1	Ф13±0.2	Ф57-0+1	3±0.2	13±0.5
13 " REEL	1005~3225	Ф330±2	Φ70Min	Ф13±0.5	Φ21±0.8	2±0.5	10±1.5

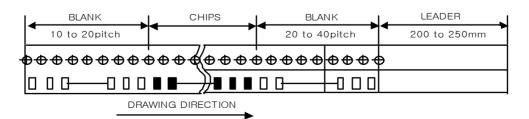
# (4) Number of Package

TYPF	FIA CODE	7"	13"		
ITPE	EIA CODE	Qt/REEL	Qt/REEL		
CS0603	CC0201	15,000			
CS1005	CC0402	10,000	50,000		
CS1608	CC0603	4,000	15,000		
CS2012	CC0805	3,000 ~ 4,000	8,000 ~ 15,000		
CS3216	CC1206	2,000 ~ 4,000	6,000 ~ 10,000		
CS3225	CC1210	1,000 ~ 3,000	4,000 ~ 10,000		
CS4520	CC1808	1,500 ~ 3,000	_		
CS4532	CC1812	500 ~ 1,000	1,500 ~ 5,000		

# (5) Tape Dimensions



TYPF	EIA CODE	Α	В	С	D	F	F	G	Н	.I
1111	LI/ CODE			<del></del>				<u> </u>	- ' '	U
CS0603	CC0201	0.67±0.05	0.37±0.05	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	2.0±0.1	4.0±0.1	1.5±0.1
CS1005	CC0402	1.15±0.1	0.65±0.1	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	2.0±0.1	4.0±0.1	1.5±0.1
CS1608	CC0603	1.9±0.2	1.10±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS2012	CC0805	2.4±0.2	1.65±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS3216	CC1206	3.6±0.2	2.00±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS3225	CC1210	3.6±0.2	2.80±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS4520	CC1808	4.8±0.2	2.3±0.2	12.0±0.3	5.5±0.1	1.75±0.1	4.0±0.1 8.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS4532	CC1812	4.9±0.2	3.6±0.2	12.0±0.3	5.5±0.1	1.75±0.1	8.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1



# 6. Caution

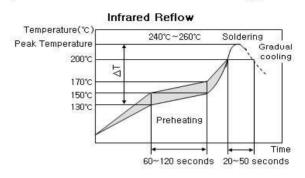
#### ▶ Reflow Soldering

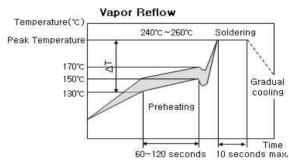
- 1. The sudden temperature change easily causes mechanical damages to ceramic components. Therefore, the preheating procedures should be required for the soldering of ceramic components.
- 2. Please refer to the recommended soldering profiles as shown in figures, and keep the temperature difference  $(\triangle T)$ within the range recommended in Table 1.

Table 1

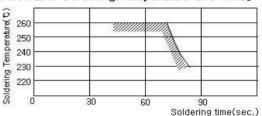
Size code	Temperature Difference			
0603, 1005, 1608, 2012, 3216	△T≤190°C			
3225size and over	△T≤130°C			

#### [Standard Conditions for Reflow Soldering]





#### [Allowable Soldering Temperature and Time]



In case of repeated soldering, the accumulated soldering time must be within the range shown above.

### ► Storage Condition

\*When Solderability is considered. Capacitor are recommended to be used in 12 months

(1) Temperature: 25°C ± 10°C

(2) Relative Humidity: Below 70% RH

- ▶ The Regulation of Environmental Pollution Materials.
  - \*Never use materials mentioned below in MLCC products regulated this document.

Pb, Cd, Hg, Cr<sup>+6</sup>, PBB(Polybromide biphenyl), PBDE(Polybrominated diphenyl ethers), asbestos.

#### \* Note

# (1) 'Aging'/'De-aging' Behavior of high dielectric MLCCs

(Typically represented by X7R, Y5V temperature characteristic of which main composition is BaTiO3)

'Aging' / 'De-aging' Behavior of high dielectric MLCCs Please note that high dielectric type dielectric Ceramic Capacitors have a "normal" 'aging' behavior / characteristic, that is; their capacitance value decreases with time from its value when it was first manufactured. From that date, the capacitance value begins to decrease at a logarithmic rate defined by:

$$C_t = C_{24} (1 - k \log 10 t)$$

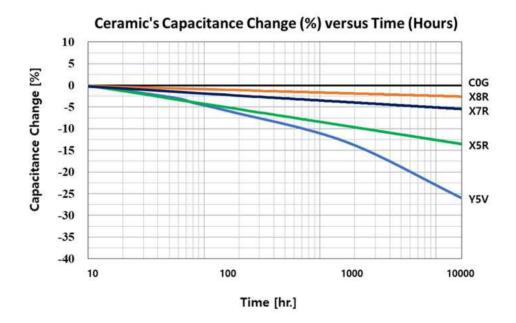
where:

Ct = Capacitance Value, t hours after the start of 'aging'

C<sub>24</sub> = Capacitance Value, 24 hours after its manufacture

k = aging constant ( capacitance decrease per decade-hour )

t = time, in hours, from the start of 'aging'



The capacitance value can be restored (a.k.a. 'de-aged') by exposing the component to elevated temperatures approaching its Curie Temperature (approximately 120°C). This 'deaging' can occur during the component's solder-assembly onto the PCB, during life or temperature cycle testing., or by 'baking 'at 150°C for about 1 hour.

- (2) Please contact our sales representatives or product engineers before using the products in this catalog for the applications listed below, which require especially high reliability for the prevention of defects which might directly damage a third party's life, body or property, or when one of our products is intended for use in applications other than those specified in this catalog.
  - ①Aircraft equipment
- ②Aerospace equipment
- 3 Undersea equipment

- ©Transportation equipment (vehicles, trains, ships, etc.)
- Traffic signal equipment Spisaster prevention / crime prevention equipment